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Oggetto : SECO launches new COM Express Type 6 module featuring Intel Core Ultra Series 3 processors

Testo del comunicato

Vedi allegato

PRESS RELEASE

SECO launches new COM Express Type 6 module featuring Intel Core Ultra Series 3 processors

Delivering next-generation AI acceleration and industrial-grade performance for edge systems

Arezzo, January 6, 2026 – SECO S.p.A. ("**SECO**" or the "**Company**") announces the launch of the **SOM-COMe-BT6-PTL**, a new COM Express Type 6 module powered by new **Intel Core Ultra Series 3 processors** which have just launched at CES in Las Vegas. The module provides customers immediate access to the latest generation of hybrid compute and AI capabilities for embedded and industrial applications.

Intel Core Ultra Series 3 processors introduce a major architectural evolution for edge workloads. They feature up to sixteen CPU cores in a redesigned hybrid structure, the new Intel NPU 5 delivering up to 50 TOPS of dedicated AI acceleration - for a total of up to 180 platform TOPS with the added power provided by CPU. The GPU features Xe3 architecture providing significant improvements in graphics and imaging performance. Support for high-speed LPDDR5x/DDR5 memory, expanded PCIe Gen4/Gen5 and Thunderbolt connectivity, and industrial-grade operating conditions make this processor family particularly suitable for AI-driven systems, advanced industrial automation, smart retail, medical imaging, multi-camera vision systems, and other latency-sensitive or graphics-intensive deployments.

With the SOM-COMe-BT6-PTL, SECO brings these next-generation capabilities to the widely adopted COM Express Type 6 Basic standard, offering a flexible and scalable building block for next-generation embedded designs.

Key features of the SOM-COMe-BT6-PTL

The new module combines performance, AI acceleration, and rich connectivity within the Basic COM Express Type 6 footprint, including:

- Support for **Intel Core Ultra Series 3 processors featuring hybrid core architecture**
- Up to 50 TOPS on the Intel NPU 5
- Up to **180 platform TOPS** AI acceleration
- Advanced graphics with **Intel Arc GPU**
- **2x So-DIMM slot, up to 128GB DDR5 memory supported**
- **PCIe Gen4/Gen5**, **USB 4.0 / Thunderbolt**, and **2.5GbE** for high-speed expansion
- **Multiple display outputs** (eDP, DP++, HDMI) for HMI and vision systems
- **Optional Industrial temperature range** for harsh environments
- Designed for long-term availability and integration into rugged and mission-critical designs

"The introduction of this solution allows our customers to leverage Intel's next gen processor family from day one, unlocking a new level of AI performance and efficiency for next-generation embedded and industrial applications. This milestone further reinforces SECO's long-standing collaboration with Intel in driving innovation at the edge," commented **Davide Catani, Chief Technology Officer of SECO.**

The new module integrates seamlessly with **Clea**, SECO's framework for IoT, AI infrastructure and device management, enabling customers to harness operational data, manage edge systems remotely, and deploy value-added services and AI applications. Through **Clea OS 2.0**, an embedded Linux distribution based on the Yocto Project, users can deploy, monitor, update, and secure edge devices at scale, while also simplifying compliance with EU cybersecurity regulations such as the CRA and RED.

Visitors can discover the SOM-COMe-BT6-PTL at the **SECO booth #8574** at CES in Las Vegas from January 6–9, 2026. For more information or to schedule a meeting, visit seco.com.

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SECO

SECO (IOT.MI) is a high-tech company that develops and manufactures cutting-edge solutions for the digitalization of industrial products and processes. SECO's hardware and software offerings enable B2B companies to easily introduce edge computing, Internet of Things, data analytics, and artificial intelligence to their businesses. SECO's technology spans across multiple fields of application, serving more than 450 customers across sectors such as medical, industrial automation, fitness, vending, transportation, and many others. Through live monitoring and smart control of in-the-field devices, SECO solutions contribute to low environmental impact business operations via a more efficient use of resources.

For more information: http://www.seco.com/

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